

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: HEINRICH HENNHÖFER ET AL.

SERIAL NO.: 09/032,305

EXAMINER: B. OKORO

FILED: February 27, 1998

GROUP: 1765

TITLE: PROCESS FOR TREATING A POLISHED SEMICONDUCTOR  
WAFER IMMEDIATELY AFTER THE SEMICONDUCTOR WAFER  
HAS BEEN POLISHED

AMENDMENT IN RESPONSE TO FIRST OFFICE ACTION

ATTN: BOX NON-FEE AMENDMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the First Office Action dated June 25, 1999,  
please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please cancel claim 2 without prejudice, and please  
incorporate the limitations thereof into claim 1 as follows:

1. (Amended) Process for treating a polished semiconductor  
wafer [comprising] consisting essentially of the steps of  
polishing a surface of a semiconductor wafer; [and]  
immediately after polishing the semiconductor wafer,  
bringing the semiconductor wafer into contact with an aqueous  
treatment agent solution for oxidizing the polished surface by  
action of the aqueous treatment agent solution; and